

IN THE CLAIMS

Claim 1(**Cancelled**).

Claim 2 (**Currently Amended**). The ~~thermoplastic heat-activatable adhesive sheet of claim 1, wherein the layer thickness method of claim 5, wherein the adhesive sheet~~ is between 10 and 100 μm thick.

Claim 3 (**Currently Amended**). The ~~thermoplastic heat-activatable adhesive sheet of claim 1 method of claim 5~~, wherein said thermoplastic polymer is selected from the group consisting of copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

Claim 4 (**Currently Amended**). The ~~thermoplastic heat-activatable adhesive sheet of claim 1 method of claim 5~~, wherein said resins are reactive resins comprising one or more members of the group consisting of epoxy resins, phenolic resins and novolak resins.

Claim 5 (**Currently Amended**). A method for bonding chip modules in card bodies which comprises bonding said chip modules in said card bodies with ~~the a~~ thermoplastic heat-activatable adhesive sheet ~~of claim 1 of an adhesive system composed of a thermoplastic polymer and optionally one or more resins, having~~

- a) a softening temperature of greater than 65°C and less than 125°C,
- b) a melt flow index (ISO 1133) of greater than 3 and less than 100 cm³/10 minutes,
- c) a storage modulus G' at 23°C, as measured by test method A, of greater than 10⁷ Pas,
- d) a loss modulus G" at 23°C, as measured by test method A, of greater than 10⁶ Pas,

and a crossover, as measured by test method A, of less than 125°C.

Claim 6 (Previously Presented). The method of claim 5, wherein said chip modules are polyimide-, polyester or epoxy-based chip modules and said card bodies are PVC, ABS, PET, PC, PP or PE card bodies.

Claim 7 (Cancelled).

Claim 8 (Currently Amended). The ~~adhesive sheet method~~ of claim 2, wherein said thickness is between 30 and 80 µm.